TU WIEN

INSTITUTE FOR MICROELECTRONICS

ESREF 2026 VIENNA

EUROPEAN SYMPOSIUM ON RELIABILITY OF ELECTRON DEVICES, FAILURE PHYSICS AND ANALYSIS

SEPTEMBER 21-24, 2026

Infineon

PATRONSHIP AND EXHIBITION

2026 VIENNA ESREF

INDEX

WELCOME TO ESREF 2026

We are delighted to welcome you to the 37th edition of **ESREF**, hosted in the historic and culturally rich city of **Vienna**, Austria, by the **Institute for Microelectronics at TU Wien**. As a city known for its long-standing contributions to science, engineering, and innovation, Vienna provides an inspiring stage for this international symposium of reliability experts.

Over the decades, ESREF has grown into a leading forum for the exchange of cutting-edge research, innovative ideas, and technological advancements in the field of micro- and nanoelectronics. This year's conference proudly continues that tradition, bringing together researchers and professionals from both academia and industry who are shaping the future of innovations in electronic devices and failure analysis.

The program spans **ten specialized tracks**, covering a wide range of timely and important topics, including reliability assessment, reliability of nanoelectronics, advances in failure analysis, power device reliability, photonics, MEMS and sensors' reliability, as well as electronics for extreme environments. Together, these sessions reflect the diversity and depth of research in our field, from novel materials and failure mechanisms to robust design strategies and applications which must perform reliably under demanding conditions.

As we gather here in Vienna, we are reminded of the critical importance of **collaboration** and **knowledge sharing** in driving progress and addressing the challenges of modern electronics. We look forward to insightful presentations, engaging discussions, and meaningful connections that will extend far beyond this event.

Lado Filipovic
Co-Chair

Michael Waltl
General Chair

RECOGNIZED GREEN EVENT

EcoEvent
Environment is VIP in Vienna

ESREF 2026 in Vienna has been officially recognized as a **Green Event** under the city's "EcoEvent" guidelines, proving that world-class science is strongly committed sustainability.

Our Green Commitments:

- Low-waste catering – seasonal, regional, and vegetarian-friendly menu options.
- Eco-friendly materials – no single-use plastics, reusable or compostable products only.
- Travel awareness – encouraging public transport, rail, and shared mobility where possible, with options to offset unavoidable flights.
- Digital-first – reduced printing, paperless proceedings, and electronic signage.
- Sustainable printing – if printed, materials will use environmentally friendly, certified paper.

Why does this matter for semiconductor research?

The semiconductor industry is accelerating its decarbonization efforts by expanding renewable energy sourcing and improving operational efficiency, while addressing challenges such as local grid limitations and other sustainability hurdles. By making **ESREF 2026** a **Green Event**, we show that scientific excellence and sustainability are not just compatible, but are mutually reinforcing. Together, we are advancing technology for a better, greener future.

MAIN PATRON SPOTLIGHT: INFINEON TECHNOLOGIES

Driving decarbonization and digitalization. Together

Semiconductors are crucial to solve the energy challenges of our time and shape the digital transformation. This is why **Infineon** is committed to actively driving decarbonization and digitalization. As a global semiconductor leader in power systems and IoT, we enable game-changing solutions for green and efficient energy, clean and safe mobility, as well as smart and secure IoT.

Energy – green and efficient: Rising demand for energy, depleted natural resources, and climate change call for more efficient ways of generating, transmitting, storing, and consuming energy. Our semiconductor solutions allow energy to be created and used more efficiently.

Mobility – clean and safe: Today, we are facing a new era of mobility with rising expectations around electrification, automation, convenience, and reliable connectivity. Our semiconductor solutions drive the transformation towards clean, safe, and smart mobility services across all means of transport.

IoT – smart and secure: As the digital transformation advances, demand for intuitive, secure, and smart 'things' is rising across everything from buildings and homes to factories and cities. Our semiconductor solutions make connected 'things' context-aware, intelligent, energy-efficient, and secure.

Infineon designs, develops, manufactures, and markets a broad range of semiconductors and semiconductor-based solutions, focusing on key markets in the automotive, industrial, and consumer sectors. Its products range from standard components to special components for digital, analog, and mixed-signal applications, all the way to data centers for artificial intelligence (AI) and certain specific consumer sectors.

Infineon Austria pools competencies for research and development, production as well as global business responsibility. It is the global competence center for power semiconductors and wideband gap materials (silicon carbide and gallium nitride and one of the strongest research companies in Austria. More information about **Infineon** in Austria: www.infineon.com/austria

With great pride, **Infineon** also supports **ESREF 2026**, underlining its commitment to advancing research, innovation, and sustainable progress in the semiconductor community.

2026 VIENNA ESREF

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Michael WALTL – Institute for Microelectronics, TU Wien, Austria

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Stay up to date
& follow us on:

STEERING COMMITTEE

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VIENNA – A CITY OF HISTORY, CULTURE AND INNOVATION

Vienna, Austria's capital, is a city where centuries of history and modern research excellence coexist in perfect harmony. Renowned for its imperial heritage, the city's historic center is a UNESCO World Heritage Site, featuring architectural landmarks such as the **Hofburg Palace, St. Stephen's Cathedral, and the State Opera House***. Strolling through its streets, visitors encounter grand Baroque buildings, elegant 19th-century boulevards, and traditionell coffee houses that have inspired thinkers, artists, and scientists for generations.

Beyond its cultural treasures, Vienna is also a hub for research and innovation. Home to prestigious institutions such as the University of Vienna (founded in 1365), **TU Wien**, the Medical University of Vienna, and many more, the city attracts leading minds from around the world. Its universities and research centers are internationally recognized for cutting-edge research in science, engineering, medicine, and the humanities, making Vienna a thriving environment for academic collaboration and technological advancement.

In Vienna, the past and the future are deeply intertwined, from the imperial architecture that tells the story of Europe's history to the vibrant research community driving innovation in areas such as quantum computing, medical technology, and semiconductor research. It is a city where conference participants can immerse themselves in cultural heritage while engaging in world-class science.

*All within a 15-minute walk from the conference venue

STATE OPERA HOUSE
Opernring 2, 1010 Vienna

ST. STEPHEN´S CATHEDRAL
Stephansplatz 3, 1010 Vienna

HOFBURG PALACE
Heldenplatz, 1010 Vienna

2026 VIENNA ESREF

TECHNISCHE UNIVERSITÄT WIEN (TU WIEN)

At the forefront of Austria's academic landscape, **TU Wien** proudly holds the title of the country's largest and most esteemed technology-focused academic institution, leading the way in pioneering research and education within the fields of technology and natural sciences. Cultivating a rich legacy spanning over two centuries, **TU Wien** remains steadfast in its commitment to the guiding principle "Technology for People". With more than 4,000 dedicated scientists propelling innovation across eight faculties and five key research areas, **TU Wien** stands as the unrivaled hub for technology and sciences in Austria!

TU Wien Main Building, Karlsplatz 13, 1040 Vienna

CONFERENCE VENUE: CAMPUS GUSSHAUS

INSTITUTE FOR MICROELECTRONICS

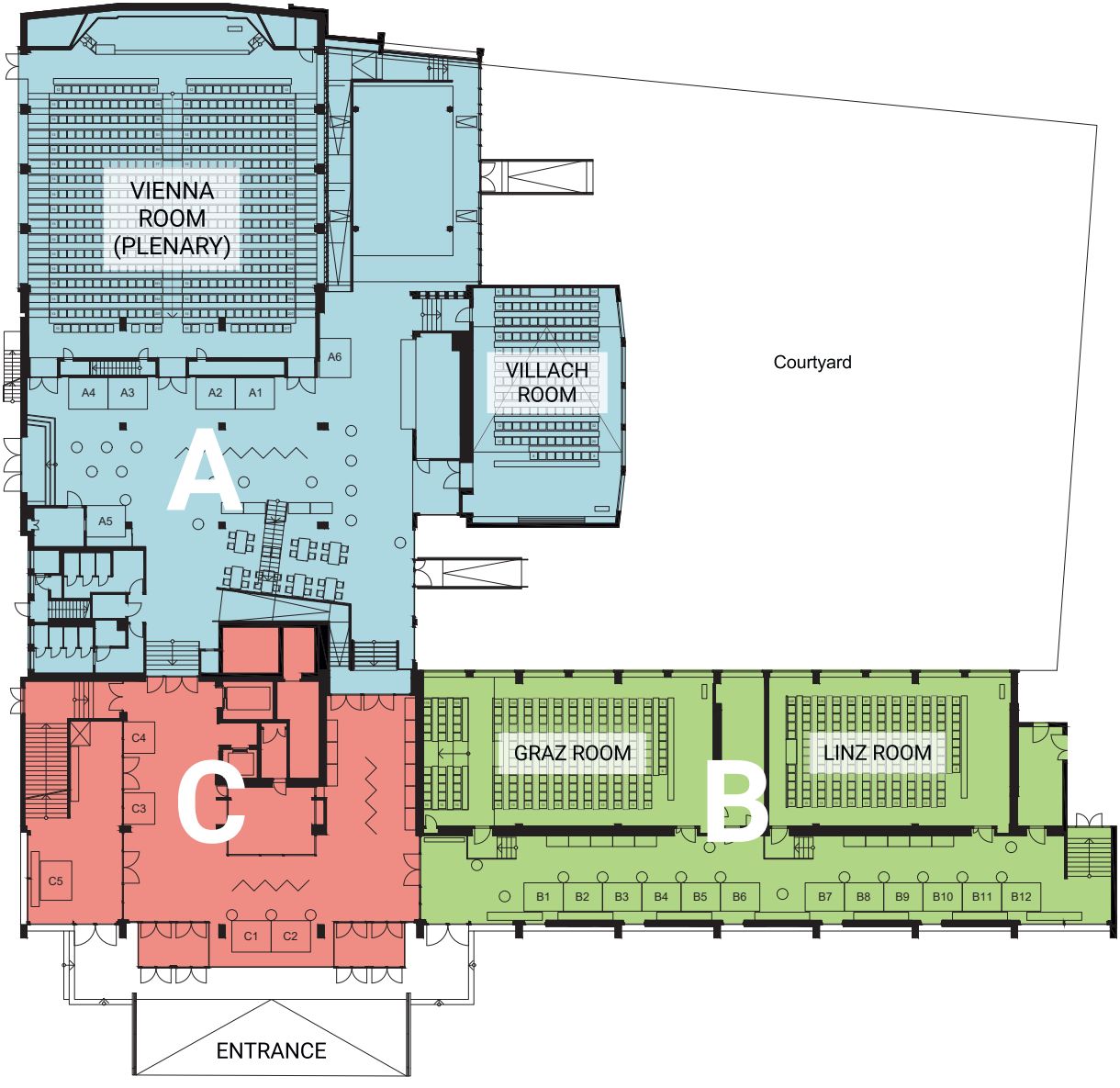
FACULTY OF ELECTRIC ENGINEERING AND INFORMATION TECHNOLOGY
Fakultät für Elektrotechnik und Informationstechnik

Semiconductors are a major focus at **TU Wien's Faculty of Electrical Engineering and Information Technology**. With state-of-the-art cleanroom and laboratory facilities, **TU Wien** provides the perfect platform for semiconductor reliability and failure analysis. Founded in 1988, the **Institute for Microelectronics** leads pioneering research in the characterization and modeling of reliability effects, spanning technologies from silicon to power devices such as SiC, GaN, and emerging 2D material. We are honored to host **ESREF 2026**.

Campus Gusshaus
Gusshausstrasse 27-29, 1040 Vienna

2026 VIENNA ESREF

FLOORPLAN: SECTIONS A, B, and C



SECTION A: CENTRAL HALL

2026 VIENNA ESREF

CENTRAL HALL

- REGISTRATION DESK
- VIENNA ROOM
- VILLACH ROOM
- EXHIBITORS
- POSTER SESSION
- CATERING AREA

A

INNOVATION WING

- GRAZ ROOM
- LINZ ROOM
- EXHIBITORS
- CATERING AREA

B

FOYER

- EXHIBITORS
- POSTER SESSION
- CATERING AREA

C

2026 VIENNA ESREF

SECTION A: CENTRAL HALL

A

REGISTRATION DESK

EXHIBITORS

CATERING AREA

POSTER SESSION

TOILETS

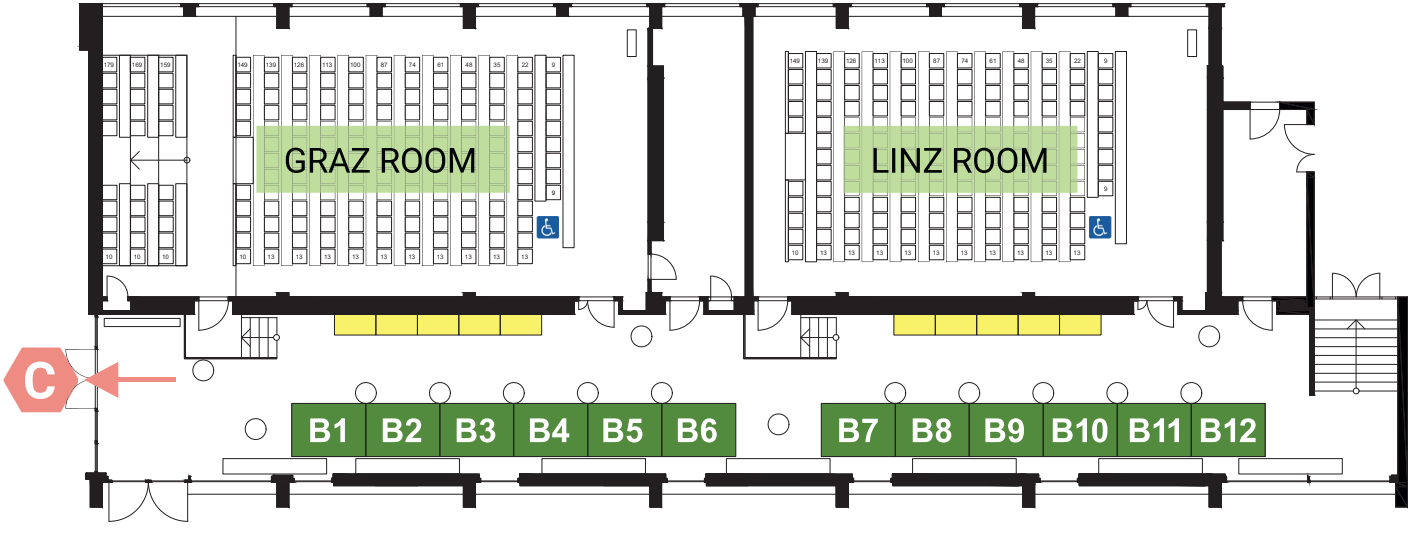
SECTION B: INNOVATION WING

2026 VIENNA ESREF

B

EXHIBITORS

CATERING AREA



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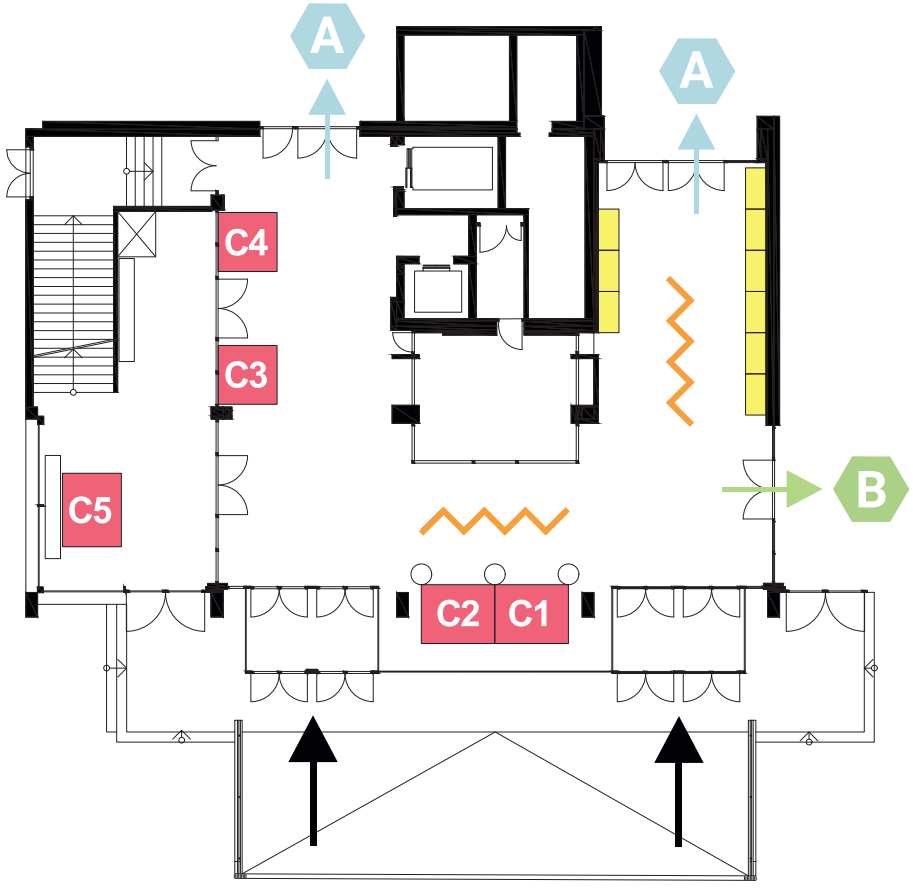
SECTION C: FOYER

C

EXHIBITORS

CATERING AREA

POSTER SESSION



INSIDE THE CONFERENCE VENUE

VILLACH ROOM

AUDITORIUM

COURTYARD

2026 VIENNA ESREF

SCOPE OF PAPERS

A Quality and Reliability Assessment Techniques and Methods for Devices and Systems

Design for reliability; Built-in reliability; Virtual qualification; Reliability simulation; Advanced models for reliability prediction; Reliability test structures; Limits to accelerated tests; Screening methods; Yield/reliability relationship; Obsolescence; Counterfeiting.

B Reliability for Nanoelectronics

Fundamental semiconductor failure mechanisms and process-related reliability issues; Passivation stability and interface degradation; Hot-carrier injection; Negative-bias temperature instability (NBTI); Time-dependent dielectric breakdown (TDDB); Reliability of high-k dielectrics, advanced gate stacks, and metal gates; Low-k dielectrics and Cu interconnects; Metal migration: electromigration, stress migration, and thermo-mechanical aspects; Non-volatile and programmable memory cell reliability; Silicon-on-Insulator (SOI) device reliability challenges; Circuit-level reliability and system integration aspects; Nanoelectronic devices and scaling-induced effects; Reliability of novel nanoelectronic materials for advanced solid-state devices; 2D materials: variability, reliability, and device integration challenges; Emerging technologies: FeFETs, FeRAM, and other beyond-CMOS concepts.

C Progress in Failure Analysis: Defect Detection and Analysis

Electron-, ion-, and optical beam techniques; Scanning probe techniques; Static or dynamic techniques; Backside techniques; Acoustic microscopy; Electric or magnetic field-based techniques; Electrical-, thermal-, and thermo-mechanical characterization; Sample preparation; Construction analysis; Failure analysis: case studies.

SCOPE OF PAPERS

D Reliability of Microwave Devices and Circuits

Reliability of GaN HEMTs, GaAs pHEMTs, InP HBTs, and SiGe devices; High-frequency degradation mechanisms and RF stress effects; Trap dynamics, charge instabilities, and current collapse in microwave devices; Reliability under high-power, high-frequency, and pulsed operation; Thermal management and self-heating challenges in RF power devices; Packaging, interconnects, and integration in RF and mm-wave systems; Reliability in applications such as 5G/6G, radar, satellite, and defense systems.

E Packaging- and Assembly Reliability and Failure Analysis

Electrical modeling and simulations for advanced packaging; Mechanical modeling and thermomechanical stress simulations; Reliability of 3D integration and through-silicon vias (TSVs); Flip-chip and solder joint reliability; Advanced substrates and interposer technologies; Chip/package interaction and system-in-package reliability; Failure analysis methods for packaging and assembly-induced degradation.

F1 Power Devices Reliability: Smart-Power Devices and Silicon Power Devices

Reliability of Smart-Power ICs and integrated drivers; Silicon MOSFET and IGBT aging mechanisms; Gate oxide integrity and charge trapping; Hot-carrier and BTI degradation in high-voltage devices; Lifetime prediction and physics-based modeling; Package stress, interconnect reliability, and thermal cycling; Robustness under automotive and industrial mission profiles.

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SCOPE OF PAPERS

F2 Power Devices Reliability: Wide-Bandgap Devices

Reliability of SiC MOSFETs and GaN HEMTs; Threshold voltage stability and interface states; Short-circuit and avalanche ruggedness in WBG devices; Defect-related degradation and trap dynamics; High-temperature and high-frequency stress testing; Packaging and integration challenges for WBG modules; Reliability in fast-charging, renewable, and aerospace applications.

F3 Power Devices Reliability: Power Electronic Systems

System-level reliability and fault tolerance; Reliability-oriented design of converters and inverters; Mission-profile-based testing and lifetime modeling; Reliability of modules, passives, and interconnects; Condition monitoring and predictive maintenance; Thermal management and cooling technologies; Standards, qualification, and field return analysis.

G Photonics Reliability

Reliability and lifetime of solar cells (Si, thin-film, perovskite, tandem); Photovoltaic degradation mechanisms and encapsulation challenges; Reliability of optoelectronic devices: lasers, LEDs, and photodetectors; Displays: OLED, micro-LED, and electronic ink stability under operation; Organic and hybrid electronics: reliability of TFTs, OLEDs, and emerging flexible devices; Packaging, encapsulation, and environmental stability in photonic and optoelectronic systems; Reliability testing methods for accelerated stress, thermal cycling, and humidity exposure.

H MEMS and Sensor Reliability

Reliability of MEMS devices: mechanical fatigue, stiction, and packaging challenges; MOEMS reliability: optical MEMS for communication, projection, and sensing; NEMS and nano-objects: scaling effects and reliability testing; Sensor reliability in harsh environments (automotive, aerospace, industrial); Bio-electronics and implantable devices: biocompatibility and long-term stability; Bio-sensors and nano-bio technologies for diagnostics and health monitoring; Environmental influences: humidity, corrosion, and contamination effects; Accelerated stress testing and lifetime prediction for micro- and nanosystems; Integration of MEMS/NEMS with ICs and heterogeneous systems.

I Extreme Environments and Radiation

Reliability of devices and circuits under extreme thermal, mechanical, and environmental stress; Electrostatic discharge (ESD) and electrical overstress (EOS) robustness; Latch-up phenomena and protection strategies in ICs and power devices; Electromagnetic compatibility (EMC) and electromagnetic interference (EMI) in circuits and systems; Radiation effects on semiconductor devices, circuits, and power electronic systems; Hardening techniques for space, avionics and other applications; System-level resilience and qualification standards for harsh environments.

J Automotive and Industrial Electronic Reliability

Reliability challenges in electric and hybrid-electric vehicles (EVs, HEVs); Batteries, supercapacitors, and energy storage systems; Powertrain electronics and drivetrain reliability; Charging stations, fast-charging systems, and vehicle-to-grid (V2G) interfaces; Thermal management solutions for automotive and industrial electronics; Reliability of electronics in harsh automotive and industrial environments; Standards, qualification, and safety requirements for mobility and industry applications.

INFORMATION FOR AUTHORS / ATTENDEES

2026 VIENNA ESREF

PAPER SUBMISSION INSTRUCTION

ESREF 2026 places great emphasis on the visibility and impact of the presented research. To ensure high scientific quality and wide dissemination, the conference is collaborating with *Microelectronics Engineering* (Elsevier) and *IEEE Xplore*. Through this collaborations, **ESREF 2026** ensures that every contribution is published in a recognized and reputable outlet, providing lasting value to both authors and the global microelectronics reliability community. Further details on publication options are available on the conference website.

ELSEVIER

Collaboration with **Microelectronics Engineering (Elsevier)**

The Technical Program Committee will invite authors to extend their abstracts to six pages and submit their work to a Special Issue of *Microelectronics Engineering* dedicated to **ESREF 2026**. Full details of this process will be provided in the official invitation email.

IEEE

Your Research Published on **IEEE Xplore**

All accepted abstracts can be published directly in *IEEE Xplore*, ensuring global visibility through one of the world's leading digital libraries.

Abstract Preparation Guidelines:
Authors are invited to submit their original research contributions to **ESREF 2026**. All submissions must follow the official **conference format** and must not exceed **four pages**, including figures and references. **LaTeX** and **Microsoft Word templates** are available on the **conference website** to assist with formatting.

Submissions must present **original research** not previously submitted or published elsewhere. All Submissions will be peer reviewed by the Technical Program Committee to ensure scientific quality and relevance.

KEY DEADLINES

2026 VIENNA ESREF

Authors:

20.03.2026:	Abstract Submission Deadline
18.05.2026:	Notification of Acceptance and Invitation to submit a paper to Microelectronics Engineering
02.06.2026:	Deadline for Microelectronics Engineering Submissions
October 2026:	Publication of Journal Papers and IEEE Conference Proceedings

Attendees[1]:

01.05.2026:	Start of Conference Registration
31.07.2026:	End of Early Bird Registration
11.09.2026:	Final Deadline for Online Registration

Conference Fees:

Details will be announced on the conference website.

[1] *Please note: One full registration per accepted contribution is required for publication, either in Microelectronics Engineering or in the IEEE Conference Proceedings.*

INFORMATION FOR AUTHORS / ATTENDEES

2026 VIENNA ESREF

SOCIAL EVENTS

Every evening: Networking in Vienna's historic and cultural venues

MONDAY, 21st September 2026:

General Chair's Reception – Kuppelsaal, TU Wien

Only a five-minute walk from the venue, the historic **Kuppelsaal,** with its iconic dome, offers an impressive setting for networking and exchange. Its nearly 200-year-old **wooden De L'Orme arch construction with a mansard roof** has been preserved, giving the hall its unmistakable character and unique atmosphere. (Karlsplatz 13, 1040 Vienna)

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TUESDAY, 22nd September 2026:

Poster Session – Conference Venue

Join us for the interactive poster session at the conference venue, where cutting-edge research will be presented in an open and engaging atmosphere. Food and drinks will be served, creating the perfect setting to enjoy lively discussions, exchange ideas, and connect with colleagues. (Gusshausstrasse 27-29, 1040 Vienna)

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WEDNESDAY, 23rd September 2026

Gala Dinner – Vienna City Hall

The **Gala Dinner** will take place in the magnificent **Vienna City Hall**, one of the city's most iconic **Neo-Gothic** landmarks. Located in the heart of Vienna, it is surrounded by historic boulevards, elegant parks, and vibrant cultural life, making it the perfect backdrop to experience Vienna's charm. Enjoy dinner in this breathtaking setting and take in the unique atmosphere of one of Europe's most beautiful city halls. (Friedrich-Schmidt-Platz 1, 1010 Vienna)

More information on the **technical and social program** will be provided on the conference webpage, via LinkedIn, and through email updates.

EXPLORING VIENNA

2026 VIENNA ESREF

VIENNA SIGHTSEEING - Hop On Hop Off, City Passes & Day Trips

Discover Vienna with the market leader Vienna Sightseeing, your No. 1 provider for city tours and Hop On Hop Off buses. From the most beautiful sights to the most popular attractions, experience sightseeing in Vienna flexibly & comfortably.

INFORMATION FOR PATRONS / EXHIBITORS

2026 VIENNA ESREF

PATRONSHIP PACKAGES

ITEM	PLATINUM SOLD OUT	GOLD 7.700€	SILVER 4.400€	BRONZE 2.800€
Patron logo displayed on the sponsors page of the ESREF website	✓	✓	✓	✓
Patron logo displayed on all pages of the ESREF website	✓	✓		
Patron description and contact details featured on the patrons page of the ESREF website	500 words	300 words	100 words	50 words
Announcement of patronship on ESREF 2026 LinkedIn page	✓	✓	✓	✓
Number of goodies to be provided for the conference bag	unlimited	max. 2	max. 1	max. 1
Patron-branded conference bags and/or refillable water bottles	exclusive			
Welcome introduction of the patron at the opening session (up to 4 Slides, max. 5 min)	✓			
Patron displayed on the tables (organized by the ESREF team) and roll-up (provided by the patrons) at the "General Chair's Reception" (on the first day of the conference)	✓			
Patron roll-up (provided by patron, up to four roll-ups) in every conference room on the podium	✓			
Patron logo displayed on conference slides shown in the halls during breaks	✓	✓	✓	✓
Conference registration ticket (Gala Dinner ticket included)	3	2	1	
Additional patron pass (Gala Dinner ticket not included)		600€	600€	600€

INFORMATION FOR PATRONS / EXHIBITORS

PATRONSHIP PACKAGES

2026 VIENNA ESREF

ITEM	PLATINUM SOLD OUT	GOLD 7.700€	SILVER 4.400€	BRONZE 2.800€
Full-color advertisment in the conference program (artwork to be provided by patron)	1 full page	1/2 page	1/4 page	
Patron logo on the back cover of the conference program	✓	✓	✓	✓
Full-color advertisment in the conference proceedings (artwork to be provided by patron)	1 full page	1/2 page	1/4 page	
Patron logo shown in the book of abstracts/conference proceedings	✓	✓	✓	✓
Patron logo featured on all newsletters and official communication e-mails	✓	✓	✓	✓
Patron logo visible at the Gala Dinner (organized by the ESREF team) in Vienna City Hall	✓	✓	✓	✓
Discount for an exhibition booth (free choice on availability)	free	40%	20%	

All prices are net prices.

To **apply for patronship** use the form on the conference website or contact the conference organizers under: **esref@tuwien.ac.at**.

Link: www.esref2026.org/forms/patronship.pdf

2026 VIENNA ESREF

EXHIBITOR PACKAGES

ITEM	Section A	Section B Section C
Early-bird fee until end of January 2026	3.700€	3.200€
Regular fee	4.200€	3.500€
Booth with company name and logo displayed, along with basic electricity supply (230V/50Hz/500W)	✓	✓
Free exhibitor pass (Gala Dinner ticket included)	1	1
Additional exhibitor pass (Gala Dinner ticket not included)	600€	600€
Company logo is displayed on the sponsors overview page of the ESREF 2026 website	✓	✓
Company logo is shown in the conference program	✓	✓
Exhibitor announcement on ESREF 2026 LinkedIn page	✓	✓

All prices are net prices.

To **apply for exhibition** use the form on the conference website or contact the conference organizers under: **esref@tuwien.ac.at**.

Link: www.esref2026.org/forms/exhibitors.pdf

KEY DEADLINES

2026 VIENNA ESREF

Patrons / Exhibitors:

01.10.2025: Sign up for Patronship or an Exhibitor Area

31.01.2026: Deadline for Early Bird Exhibitor Registration

31.07.2026: Final Deadline for Patron and Exhibitor Registration

General Terms & Conditions:

By attending **ESREF 2026**, you agree to the **General Terms & Conditions,** which can be found on the conference website.

Link: www.esref2026.org/forms/termsandconditions.pdf

2026 VIENNA ESREF

HOW TO REACH THE VENUE:

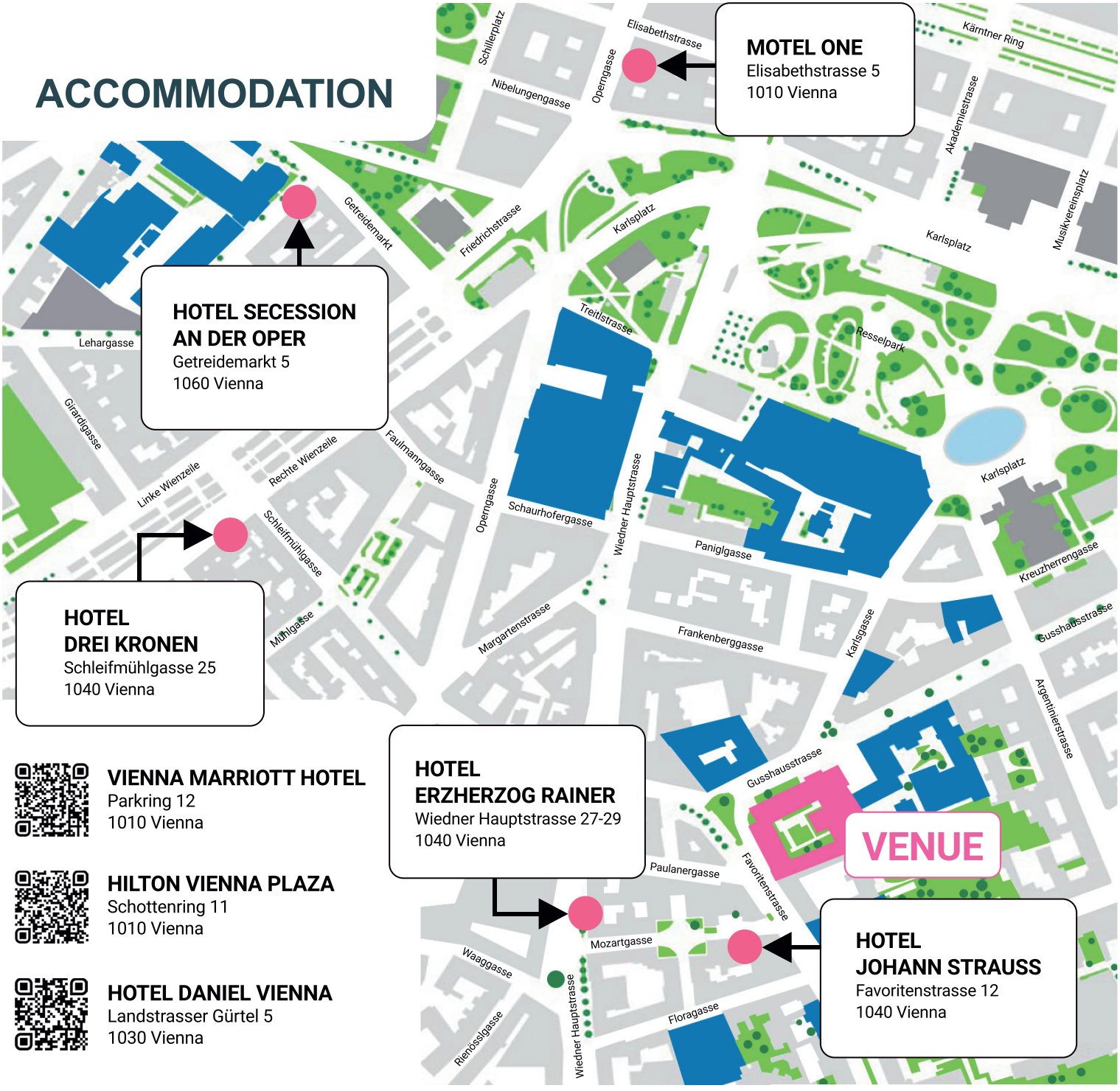
By public transport: The easiest way is to take the metro lines U1, U2 or U4 to Karlsplatz or U1 to Taubstummengasse. From either station, the venue is just a five-minute walk away, allowing participants to arrive quickly and comfortably.

By car: There are expressways from the west (A1), the south/east (A2) and the north (A22) leading to Vienna. There are also 24-hour public parking garages: *Karlsplatz garage* (Mattiellistraße 2-4, 1040 Vienna) and *TU Wien garage* (Operngasse 13, 1040 Vienna)

About the Venue:

The venue itself offers both state-of-the-art conference facilities and inviting spaces for networking and informal exchanges. A welcoming inner courtyard, directly accessible from the central hall, provides a peaceful open-air setting to relax between sessions. In addition, our rooftop terrace is open to all participants, offering a unique view over Vienna and a pleasant atmosphere for conversations, breaks, and evening receptions.

ACCOMMODATION



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Elisabethstrasse 5
1010 Vienna

HOTEL SECESSION AN DER OPER
Getreidemarkt 5
1060 Vienna

HOTEL DREI KRONEN
Schleifmühlgasse 25
1040 Vienna

HOTEL ERZHERZOG RAINER
Wiedner Hauptstrasse 27-29
1040 Vienna

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1040 Vienna

VIENNA MARRIOTT HOTEL
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1010 Vienna

HILTON VIENNA PLAZA
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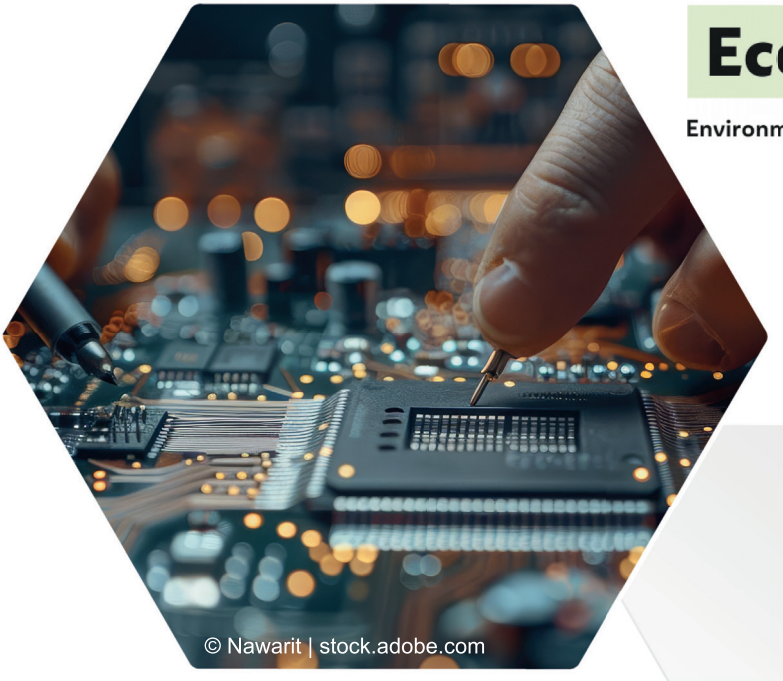
1010 Vienna

HOTEL DANIEL VIENNA
Landstrasser Gürtel 5
1030 Vienna

EcoEvent

Environment is VIP in Vienna



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